

# Wafer UV Resist Hardening System



## FEATURES :

1. High-intensity ultraviolet irradiation, high throughput
2. Min.  $650 \text{ m W / cm}^2$  ( at wavelengths ranging from 220 to 450 nm )
3. Wafer size : 300 / 200 / 150 mm
4. Stage temp. rise / cool rate fast ( rise:  $2.0 \pm 0.2^\circ \text{C / sec}$ ; cool:  $3^\circ \text{C / sec}$  )
5. UV distribution: Max.  $\pm 10\%$  ( measured at 5 points on a wafer in H mode )
6. Clean, fast wafer handling
7. Space-saving / Complete safety design



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## **APPLICATIONS :**

- 1.Enhancement of thermal resistance of photoresist and degassing from photoresist prior to ion implantation process
- 2.Erasure of electrical charge and removal of stress

## **SPECIFICATION:**

ITEM	SPECIFICATION
Wafer size	Φ300 / 200 / 150 mm
M / C size ( W x D x H )	195 X 200 X 250 cm
Power supply	AC 380V / 220V 50 / 60Hz 3 Φ
UV Intensity	Min. 650 m W /cm <sup>2</sup> ( at wavelengths ranging from 220 to 450 nm )
Max.hot plate temperature	250 °C
Hot-plate temperature rise rate	$T/\Delta t=2.0\pm 0.2^{\circ}\text{C} / \text{sec}$ ( $\Delta T\geq 150^{\circ}\text{C}$ , H-mode )
Wafer transfer mechanism	Wafer robot
Load port	Manual / Auto
System type	PC BASE MMI
Safety certification	SEMI S2 ( option )